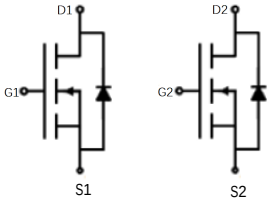
N-Channel Enhancement Mode Power MOSFET

Description

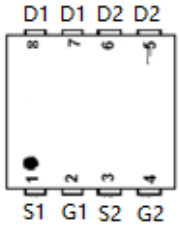
The XPX6NN9U5RD uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.



Schematic Diagram

General Features

- V_{DS} 60V
- I_D (at V_{GS} = 10V) 40A
- $R_{DS(ON)}$ (at V_{GS} = 10V) < 9.5mΩ
- $R_{DS(ON)}$ (at V_{GS} = 4.5V) < 15mΩ
- 100% Avalanche Tested
- RoHS Compliant



Marking and pin assignment

Application

- Synchronous Rectification in SMPS or LED Driver
- UPS
- Motor Control
- BMS
- High Frequency Circuit


DFN5X6双基

Device	Package	Marking	Packaging
XPX6NN9U5RD	DFN5X6		2500pcs/Reel

Absolute Maximum Ratings T_C = 25ºC, unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Continuous Drain Current	I_D	40	A
Pulsed Drain Current (note1)	I_{DM}	140	A
Gate-Source Voltage	V_{GS}	±20	V
Power Dissipation	P_D	62	W
Single pulse avalanche energy （note3）	E_{AS}	20	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	ºC

Thermal Resistance

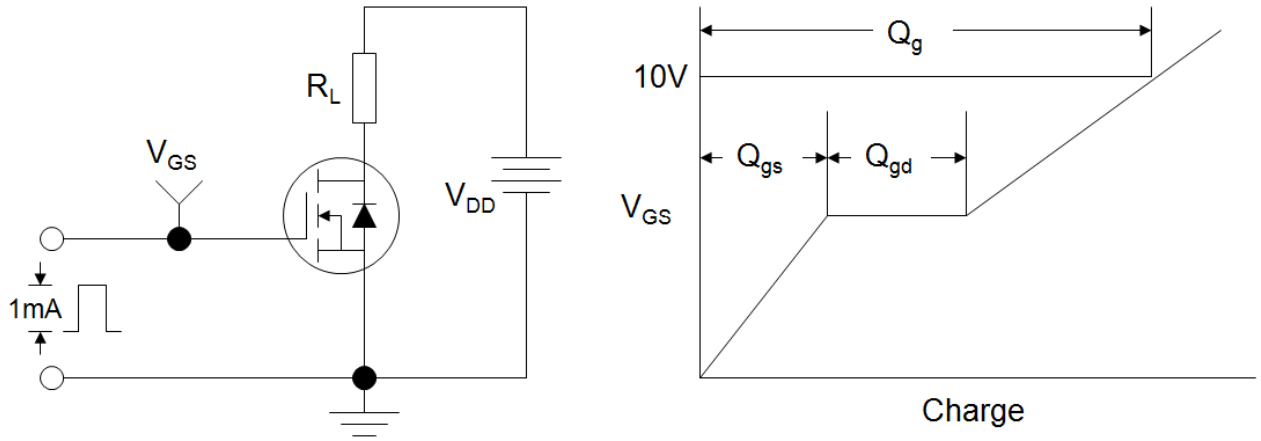
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	65	ºC/W
Thermal Resistance, Junction-to-Case	R_{thJC}	2	ºC/W

Specifications T_J = 25ºC, unless otherwise noted						
Parameter	**Symbol**	**Test Conditions**	**Value**			**Unit**
			Min.	**Typ.**	**Max.**	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	60	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 60V, V_{GS} = 0V	--	--	1	μA
Gate-Source Leakage	I_{GSS}	V_{GS} = ±20V	--	--	±100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	1	1.7	2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS} = 10V, I_D = 12A	--	8.3	9.5	mΩ
		V_{GS} = 4.5V, I_D = 12A	--	10.4	15	
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=20A		26	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 30V, f = 1.0MHz	--	1622	--	pF
Output Capacitance	C_{oss}		--	414	--	
Reverse Transfer Capacitance	C_{rss}		--	3	--	
Total Gate Charge	Q_g	V_{DS} = 30V, I_D = 20A, V_{GS} = 10V	--	24	--	nC
Gate-Source Charge	Q_{gs}		--	5	--	
Gate-Drain Charge	Q_{gd}		--	3	--	
Turn-on Delay Time	$t_{d(on)}$	V_{DS} = 30V, I_D = 20A, R_G = 10Ω	--	9	--	ns
Turn-on Rise Time	t_r		--	4	--	
Turn-off Delay Time	$t_{d(off)}$		--	29	--	
Turn-off Fall Time	t_f		--	4	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	T_C = 25ºC	--	--	12	A
Body Diode Voltage	V_{SD}	T_J = 25ºC, I_S = 20A, V_{GS} =0V	--	--	1.2	V

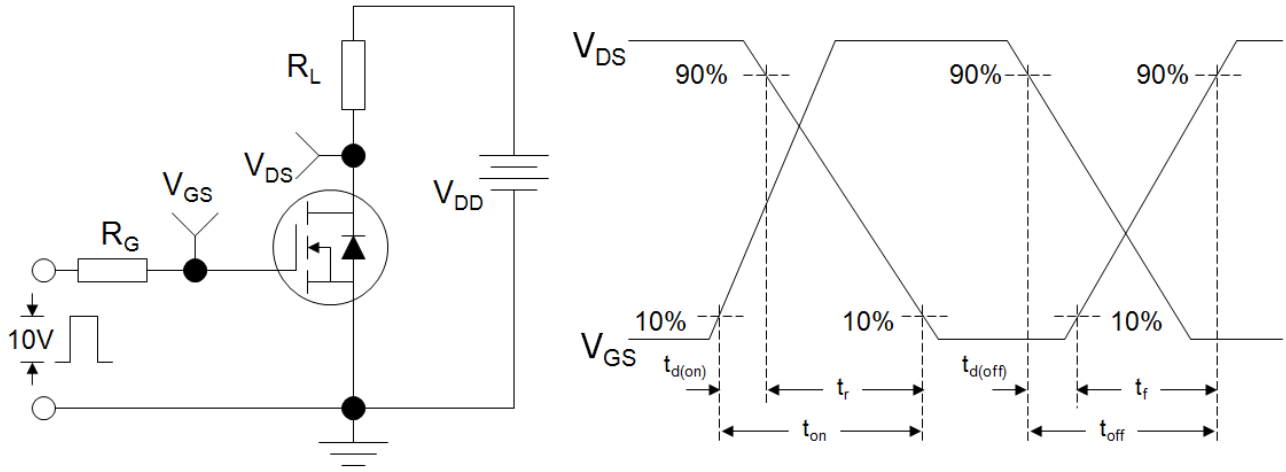
Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical R_G
3. EAS condition : Tj=25℃ ,VDD=50V,VGS=10V,L=0.5mH,Rg=25Ω

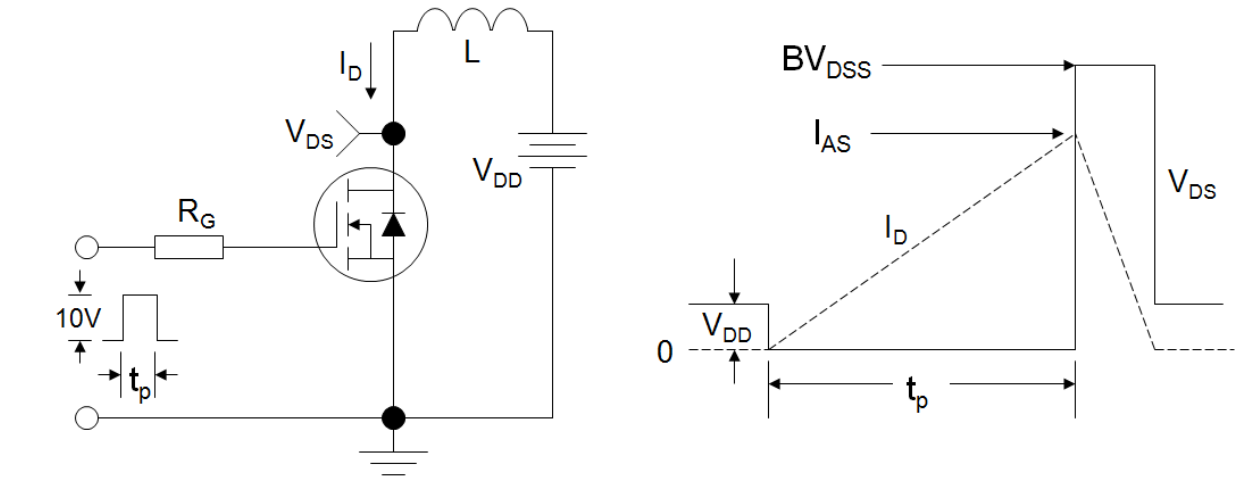
Gate Charge Test Circuit



EAS Test Circuit



Switch Time Test Circuit



Typical Characteristics T_J = 25ºC, unless otherwise noted

Figure 1. Output Characteristics

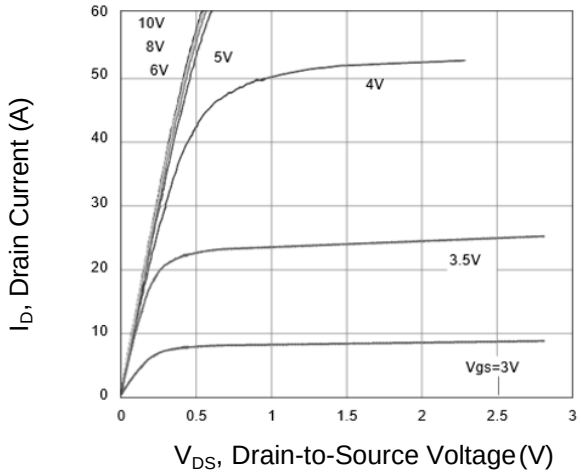


Figure 2. Transfer Characteristics

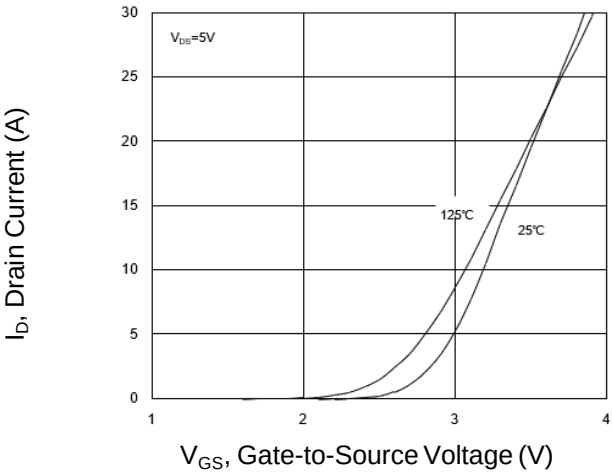


Figure 3.Rdson-Drain Current

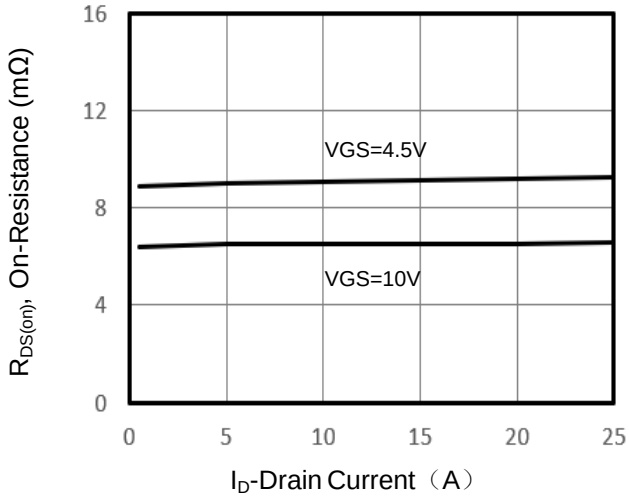


Figure 4. Gate Charge

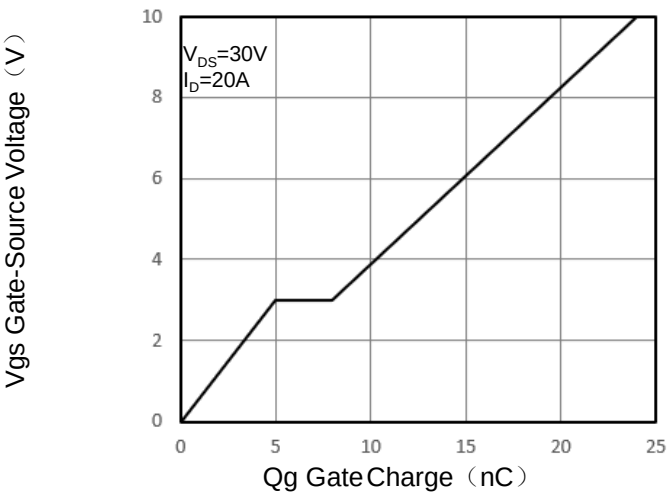


Figure 5. Capacitance vs Vds

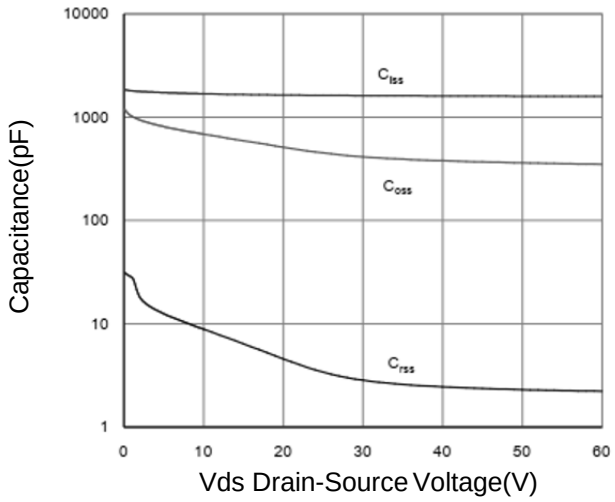
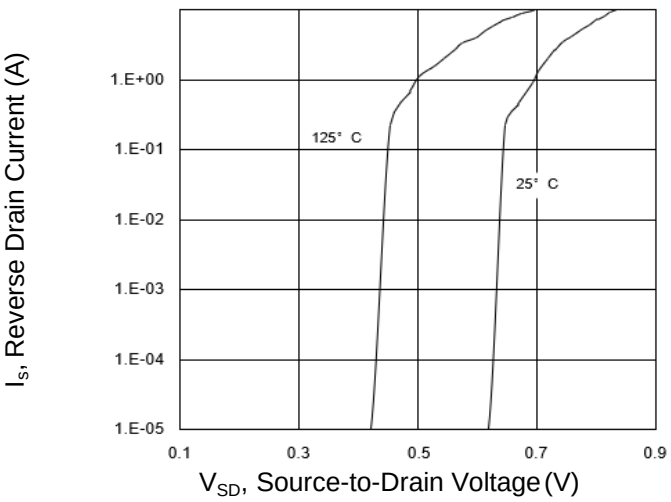


Figure 6. Source-Drain Diode Forward



Typical Characteristics T_J = 25ºC, unless otherwise noted

Figure 7. Drain-Source On-Resistance

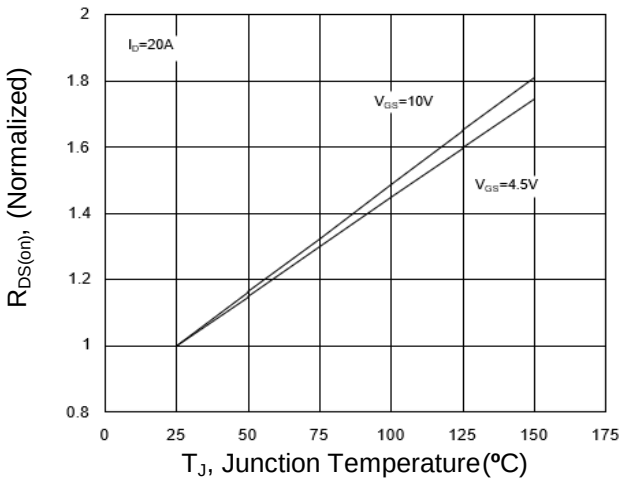


Figure 8. On-Resistance vs. Gate-Source Voltage

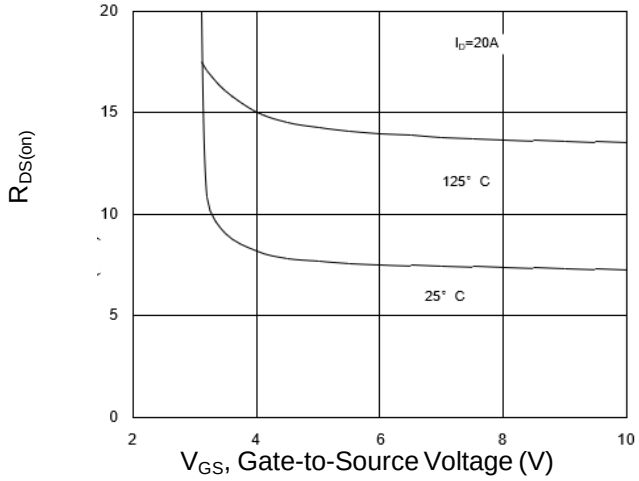


Figure 9. Normalized Maximum Transient Thermal Impedance

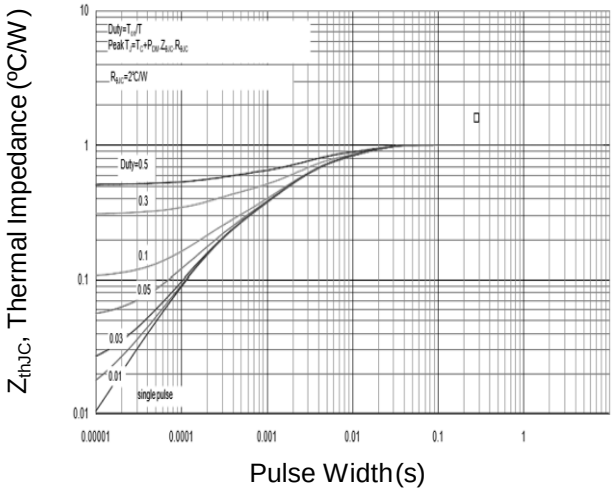
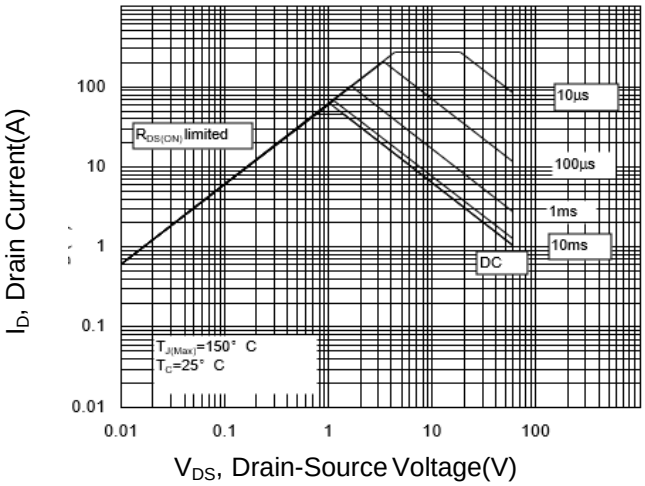
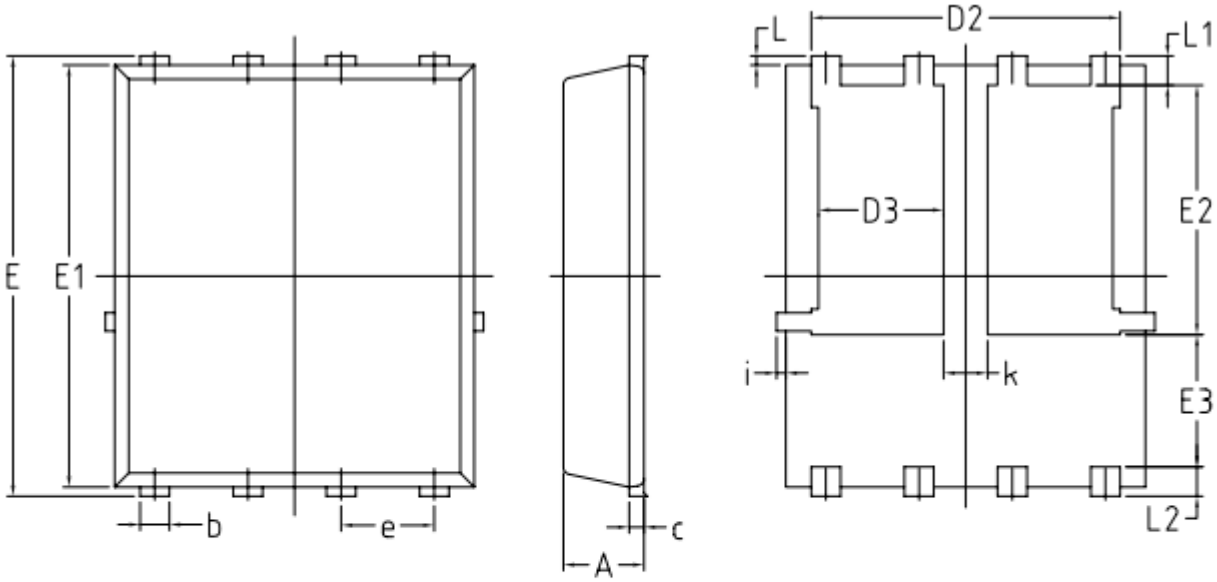
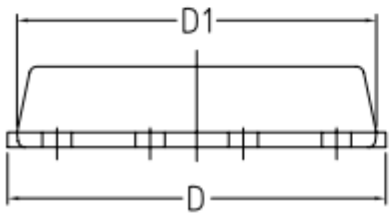


Figure 10. Safe Operation Area







SYMBOL	COMMON			
	MM		INCH	
	MIN.	MAX.	MIN.	MAX.
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.203 BSC		0.0080 BSC	
D	4.80	5.40	0.1890	0.2126
D1	4.80	5.00	0.1890	0.1969
D2	4.11	4.31	0.1620	0.1700
D3	1.60	1.80	0.0629	0.0708
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	3.30	3.50	0.1300	0.1378
E3	1.70	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0019	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
i	/	0.18	/	0.0070
k	0.5	0.7	0.0197	0.0276